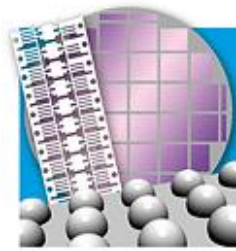


HYDRON SE 220

pH-neutral defluxing agent for semiconductor electronics



HYDRON® SE 220 is a water-based, single-phase cleaning agent specifically developed for the use in dip tank processes. HYDRON® SE 220 reliably removes flux residues from all kind of semiconductor electronics, such as leadframes, discrete devices, power modules and power LEDs as well as flip chip or CMOS, i.e. after die attach. Due to its single-phase formulation, the cleaning agent shows an excellent processability and good rinsing performance, providing optimal surface characteristics for subsequent processes such as wire bonding or molding. HYDRON® SE 220 is pH-neutral and thus ensures excellent material compatibility.

Areas of application: defluxing of semiconductor electronics (leadframes, discrete devices, power modules & -LEDs, flip chip, CMOS)			Additional product information:
Solder Paste	Low solids	+	Technical Information 3: Material compatibility overview
	Water-soluble (OA)	++	
	No clean	++	
	High solids	++	
	Lead-based	+	

++ highly recommended, best results + recommended 0 possible - not recommended

Technical Centers - ① America, ② Europe, ③ Malaysia, ④ North-China, ⑤ South-China Cleaning Process Solutions under Production Floor Conditions



Advantages compared to other cleaners:

- Due to its single-phase formulation, HYDRON® SE 220 can be easily processed and provides excellent performance in dip tank processes.
- HYDRON® SE 220 can be easily rinsed off with DI-water without leaving any residues
- The cleaning agent is pH-neutral, therefore provides excellent material compatibility, specifically with dies, no attack of chip passivations.
- HYDRON® SE 220 provides stainless, activated copper surfaces for subsequent processes such as wire bonding, moulding and adhesive bonding and retains these activated surfaces over a temporary storage time.
- HYDRON® SE 220 has no flash point and thus can be applied in dip tank equipment without explosion proof.
- Formulated free of halogenated compounds and has a low odor.

Please refer to the material compatibility list (Technical Information 3) before cleaning plastics.



Process Steps	1. Cleaning	2. Rinsing	3. Drying
Ultrasonic (US) / Spray under immersion (SUI)	HYDRON® SE 220	DI-water ¹	Hot air or circulating air

¹The DI-water temperature should be between 20-40°C/68-104°F.

Technical Data		
Please note that the following information represents HYDRON® SE 220 at 25 % concentration.		
Density	(g/ccm) at 20°C/68°F	0,99
Surface tension	(mN/m) at 25°C/77°F	26,0
Boiling point	°C/°F	>98°C / > 208°F
Flash point	°C/°F	None
pH-value	10g/l H ₂ O	Neutral
Vapor pressure	(mbar) at 20°C/68°F	Approx. 20
Cleaning temperature	°C/°F	40 - 60°C / 104 - 140°F
Solubility in water		Soluble
Application concentration ¹	Concentrate	20-25 %
HMIS Rating	Health-Flammability-Reactivity	1 - 0 - 0

¹The concentrate of HYDRON® SE 220 has to be diluted in DI-water.

PRODUCT FEATURES



Extensively tested and suitable for cleaning of lead-free solder pastes



Product is free of any critical substances according to SIN & SVHC lists



100% compliance with EU guidelines (RoHS 1 & 2, WEEE)

Filter recommendation

- To take full advantage of the cleaner and further expand the bath life of HYDRON® SE 220, filtration is recommended.

Environmental, health and safety regulations:

- HYDRON® SE 220 is water-based and biodegradable.
- HYDRON® SE 220 is formulated free of any halogenated compounds and environmentally friendly.
- Refer to the MSDS for specific handling precautions and instructions.

Availability/Storage:

- HYDRON® SE 220 is available as a concentrate in 1l bottles, 5l or 25l containers and 200l drums.
- Store HYDRON® SE 220 in the original container at a temperature between 5 - 30°C / 41 - 86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

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